

Final Product/Process Change Notification Document #:FPCN23822XA

Issue Date: 13 Sep 2022

Title of Change:		Transfer of N24S128C4DYT3G and N24S64C4DYT3G from FCI to ASE CL (bump) and onsemi Tarlac, Philippines (FT/singulation/TnR).		
Proposed First Ship date:	20 Dec 2022 or earlier if approved by customer			
Contact Information:	Contact your local onse	Contact your local onsemi Sales Office or Doina.Patrascu@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Additional Reliability Data:	Contact your local onse	Contact your local onsemi Sales Office or <u>Joe.Chapple@onsemi.com</u>		
Type of Notification:	90 days prior to implen onsemi will consider th	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	Traceability of change will be on the date code			
Change Category:	Test Change, Assembly	Test Change, Assembly Change		
Change Sub-Category(s):	Manufacturing Site Tra	Manufacturing Site Transfer		
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Tarlac, Philippines		ASECL, Taiwan (ChungLi)		
		Flipchip International, USA		

Description and Purpose:

	From	То	
Bump, back grind, backside coating and marking	Flipchip International, USA	ASE CL, Taiwan	
Final Test, singulation and TnR	Flipchip International, USA	onsemi Tarlac, Philippines	
Bump/Pillar Structure	CRC2348 (Sumitomo)	Hitachi Dupont HD8820	
RDL Material, Thickness	Cu; 6.25um ± 1.25um (include seedlayer) Cu; 6.3um ± 1.5um (include see		
Polymer Material, Thickness	CRC2348 (Sumitomo) No change for thickness	` ' Hitachi Dunont HD8820	
Solderball Material	SAC305	SAC405	

There is no product marking change as result of this change.

TEM001793 Rev. F Page 1 of 2



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Reliability Data Summary:

QV DEVICE NAME: N24S128C4DYT3G

RMS: <u>S83890</u> PACKAGE: <u>WLCSP 4</u>

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
TC	JESD22-A104	Ta= -40°C to +125°C	1000 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	3x reflow	0/240

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number		Qualification Vehicle	
	N24S64C4DYT3G	N24S128C4DYT3G	
	N24S128C4DYT3G	N24S128C4DYT3G	

TEM001793 Rev. F Page 2 of 2



Appendix A: Changed Products

PCN#: FPCN23822XA Issue Date: Sep 12, 2022

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
N24S128C4DYT3G		N24S128C4DYT3G	NA	